

Japan TC Chapter 3D Packaging & Integration (3DP&I) Global Technical Committee

Liaison Report | June 2021

V1.1

Meeting Information

- Last meeting
 - Friday, May 28, 2021 at the SEMI Standards Japan Spring Meetings
 - Web Conference
- Next meeting
 - Friday, October 22, 2021
 - Web Conference

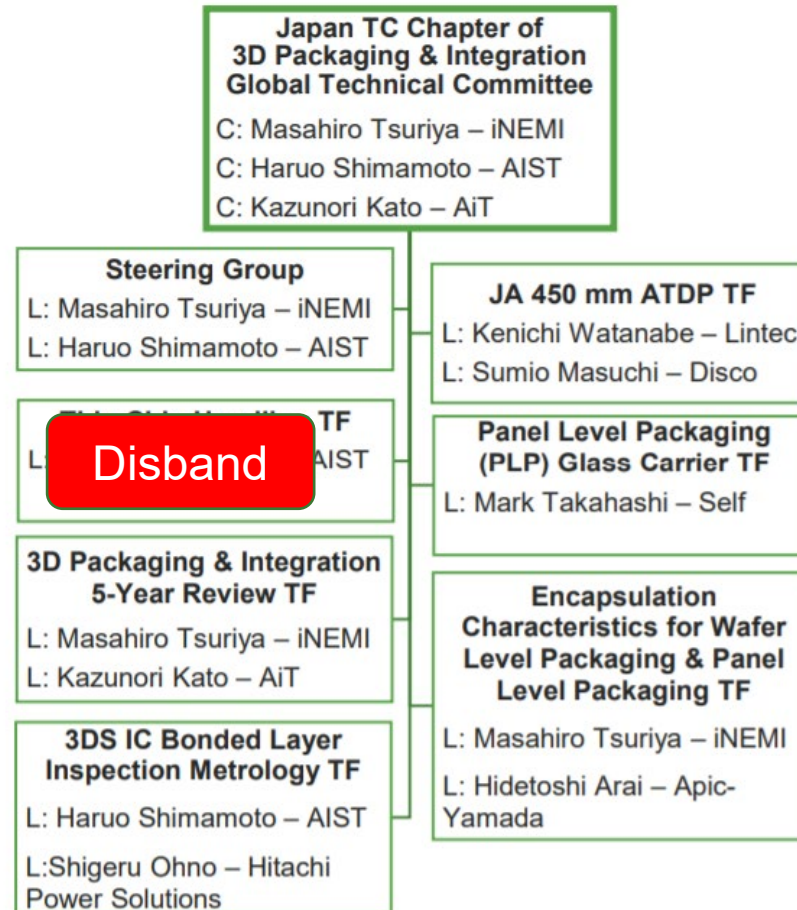
<http://www.semi.org/en/standards-events>

Committee Structure Changes



Previous WG/TF/SC Name	New WG/TF/SC Name or Status Change
Thin Chip Handling TF	Disband

Organization Chart



Ballot Results



Doc #	Document Title	TC Chapter Action
6703	Revision to SEMI G63-95 (Reapproved 0811) "Test Method for Measurement of Die Shear Strength"	Failed due to insufficient rate and return to TF for rework

Note 1: **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

Note 2: **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

Authorized Ballots

Doc #	When	TF	Document Title/Details
6703A	Cycle 8/9-2021	3D Packaging & Integration 5 Year Review TF	Revision to SEMI G63-95 (Reapproved 0811) "Test Method for Measurement of Die Shear Strength"

Task Force Highlights[1/3]



- Encapsulation Characteristics for Wafer Level Package and Panel Level Packaging TF
 - Taskforce Kick-off: November 18, 2020
 - Under development of standard document drafts for 8 encapsulate materials characteristics and 3 items for performances
 - SNARFs approval requests for 8 material characteristics
 - Ballot6706,6707,6708,6709,6710,6711,6712
 - Plan to develop final ballot draft by the end of Q3.
- Panel Level Packaging (PLP) Glass Carrier TF
 - Reviewed ballot 6590, New Standard: Specification for Glass Carrier Characteristics for Panel Level Packaging (PLP) Applications

Task Force Highlights[2/3]



- Five Years Review TF
 - Completed the review and submitted the ballots for 2020 required review documents.
 - Will start for 2021 review needed
- 3DS IC Bonded Layer Inspection Metrology TF
 - Pre-trial using the SEMATECH sample was done by Aug. 2020.
 - Detectable void size by the nominal frequency of the transducer was defined.
 - A sample for the feasibility study was designed by Sept. 2020.
 - Manufacturing the sample for the feasibility study is delayed due to COVID and equipment trouble.

Task Force Highlights[3/3]

- 3D Packaging & Integration Steering Group WG
 - Continue to brainstorm the potential areas of SEMI Standard.
 - Example: RDL Adhesion Strength Measurement/Metrology Proposal
 - Share the taskforce activities progress
 - Work on the joint discussion with TWN TC (held meeting on August 2020)
 - Displayed 3 posters at SEMICON Japan 2020

Thank you!

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